L Number	Hits	Search Text	DB	Time stamp
	87	stack near4 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB;	2003/05/13 09:31
			EPO; JPO; DERWENT;	
	6	(stack near4 heat adj sink.ti,ab,clm.)	IBM_TDB USPAT;	2003/05/13
		and (rubber or elastic)	US-PGPUB;	10:14
			EPO; JPO; DERWENT;	
	5	(stack near4 heat adj sink.ti,ab,clm.)	IBM_TDB USPAT;	2003/05/13
		and (rubber or elastic or spacer) near12	US-PGPUB;	10:15
		(insulat\$3 or isolat\$3)	EPO; JPO; DERWENT;	
	29	riser near6 heat adj sink	IBM_TDB USPAT;	2003/05/13
		January Mode adj Sink	US-PGPUB;	11:04
			EPO; JPO; DERWENT;	:
			IBM TDB	
i	2		USPĀT;	2003/05/13
		or flow or fluid or coolant or water)	US-PGPUB; EPO; JPO;	11:05
			DERWENT;	
0	28	riser near10 (liquid or flow or fluid or	IBM_TDB USPAT;	2003/05/13
		coolant or water) and heat adj	US-PGPUB;	11:53
4		sink.ti,ab,clm.	EPO; JPO; DERWENT;	
3	2	(UE704020U)	IBM_TDB	
٠	۷	("5794839").PN.	USPAT; US-PGPUB;	2003/05/13
			EPO; JPO;	13.19
			DERWENT;	
4	7	semiconductor adj laser.ti,ab,clm. and	IBM_TDB USPAT;	2003/05/13
		heat adj sink.ti,ab,clm. and (stack or	US-PGPUB;	14:10
1		stacked) near3 heat adj sink	EPO; JPO; DERWENT;	
_			IBM TDB	
5	1	heat adj sink.ti,ab,clm. and (stack or	USPAT;	2003/05/13
		stacked) near3 heat adj sink and (upper adj electrode near20 lower adj electrode)	US-PGPUB; EPO; JPO;	14:08
			DERWENT;	
6	2	semiconductor.ti,ab,clm. and heat adj	IBM_TDB USPAT;	2002/05/12
	-	sink.ti,ab,clm. and (stack or stacked)	USPAT; US-PGPUB;	2003/05/13
		adj heat adj "sinks" and (top upper) adj	EPO; JPO;	
		electrode	DERWENT; IBM_TDB	
, C	36		USPAT;	2003/05/13
			US-PGPUB;	14:28
			EPO; JPO; DERWENT;	
1			IBM_TDB	
L	9		USPAT;	2003/05/13
			US-PGPUB; EPO; JPO;	15:21
			DERWENT;	
3	174	257/625	IBM_TDB	2003/05/13
	1,1	,	USPAT; US-PGPUB;	16:09
			EPO; JPO;	-
			DERWENT;	

24	8124	((257/625) or (257/675) or (257/717) or	IICDAT.	2002/05/12
		(257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 16:23
26	1	(((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (riser guide guiding) nearl2 (flow liquid water coolant) and (stack stacked) near2 heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:13
27	2	(((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and stacked adj heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 16:39
28	10		IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 16:45
32	0	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:46
33	2	and (first upper top) adj electrode ((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 16:49
34	0	and electrode stacked adj heat adj sinks.ti,ab,clm. and semiconductor adj2 (element device) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 16:51
35		(stack stacking stacked) near12 heat adj sinks and semiconductor adj2 (element device) and ((top upper) adj electrode)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13
36		("4631573").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13
37	!	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 17:31
38	1	stacked.ti,ab,clm. and heat adj sink.ti,ab,clm. and (electronic or semiconductor) adj (device or element) and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 19:34
39	0	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 19:35
40	74	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and series	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:53

41	8	stacked near3 active near3 region near3 monolithic near3 laser near3 array	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 19:55
42	2	("5157680").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 19:55
43	20	stacked near12 active near12 laser near12 array	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/13 20:35
4 4	2	("4791634").PN.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/05/13 21:07
45	2	("6144683").PN.	EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/05/13
i i			US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	21:08
46	0	("jp-8181392\$-\$.did.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/13 21:09
47	2	jp-08181392\$-\$.did.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/13 21:09
48	0	bell.in. and morrison.in. and law.in. and malcolm.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/13 21:11
49	1	gb-1597829\$-\$.did.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/05/13 21:12
-	2	jp-09102568\$-\$.did.	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/05/13
-	2	ijp-08227953\$-\$.did.	EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/08/06
_	2	jp-08139479\$-\$.did.	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/08/06
	_		US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	16:24
-	3	("5785754").PN.	USPAT; US-PGPUB; EFO, JPO, DERWENT;	2002/08/06 16:24
-	2008	((372/34) or (372/35) or (372/36)).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 15:24
			. IBM_TDB	

	996	heat adj sink.ti. and 257/\$6.ccls.	USPAT;	2002/08/07
			US-PGPUB; EPO; JPO; DERWENT; IBM TDB	07:45
=	33	heat adj sink.ti. and liquid.ti,ab. and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 15:28
	20	((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and laser.ti,ab. and heat adj sink.ti,ab. and (liquid or water).ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 08:27
· -	8	US-4791634-\$ or US-4712609-\$ or US-3764935-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$).did.	USPAT; US-PGPUB; JPO	2002/08/07 08:49
-		(257/365).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/08 15:44
	6068	(((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/09 12:50
	307	((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:52
-	110	(((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:53
_	63	((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:55
	40	(((((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT	2002/08/09 12:56
-	44	((((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_IDB	2002/08/09
<u>-</u>		heat adj sink.ti. and liquid.ti,ab. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 15:29

_	33	heat adj sink.ti. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 15:29
-	10026	heat adj sink and upper near12 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 11:24
-	710	heat adj sink.ti. and upper near12 lower	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/23 11:25
	70	heat adj sink.ti. and upper near12 lower near12 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/23 11:26
-	30	heat adj sink.ti. and upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23
_	2	heat adj sink.ti. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/23
-		heat adj sink.ti,ab. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/23
-		heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/23
-	4	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower near6 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/23 11:52
-	6	heat adj sink.ti,ab. and (groove or trench) near18 ((upper near18 lower) near18 (face or main adj surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/23
_	4163	((257/712) or (257/713) or (257/714) or (257/715)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 14:08
- :	1156	(372/34).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 15:25
- :	423	(372/35).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23
-	661	(372/36).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 15:26
			IBM_TDB	

	1004	1257 (712) CCI S		0000/00/00
_	1884	(257/712).CCLS.	USPAT;	2002/08/23
			US-PGPUB;	15:26
			EPO; JPO;	
			DERWENT;	
	050	/057/710\	IBM_TDB	
_	958	(257/713).CCLS.	USPAT;	2002/08/23
			US-PGPUB;	15:26
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1193	(257/714).CCLS.	USPĀT;	2002/08/23
			US-PGPUB;	15:26
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
: -	493	(257/715).CCLS.	USPAT;	2002/08/23
		()·	US-PGPUB;	15:26
			EPO; JPO;	13.20
			DERWENT;	
_ !	6144	((372/34).CCLS.) or ((372/35).CCLS.) or	IBM_TDB	2002/00/22
	OTAA		USPAT;	2002/08/23
		((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	15:27
		((257/713).CCLS.) or ((257/714).CCLS.) or	EPO; JPO;	
		((257/715).CCLS.)	DERWENT;	
1			IBM_TDB	
-	4269	(((372/34).CCLS.) or ((372/35).CCLS.) or	USPAT;	2002/08/23
		((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	15:28
		((257/713).CCLS.) or ((257/714).CCLS.) or	EPO; JPO;	
		((257/715).CCLS.)) and (heat adj removal	DERWENT;	
		or heat adj sink or coolant or cooling)	IBM TDB	
-	3590	(((372/34).CCLS.) or ((372/35).CCLS.) or	USPAT;	2002/08/23
		((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	15:29
		((257/713).CCLS.) or ((257/714).CCLS.) or	EPO; JPO;	10.25
		((257/715).CCLS.)) and (heat adj removal	DERWENT;	
		or heat adj sink or coolant or	IBM TDB	
		cooling).ti,ab,clm.	TDII_TDB	
-	1280		USPAT;	2002/08/23
	1200	((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	
		((257/713).CCLS.) or ((257/714).CCLS.) or		15:29
		((257/715).CCLS.)) and (heat adj removal	EPO; JPO;	i
		or heat adj sink or coolant or	DERWENT;	
			IBM_TDB	
	262	cooling).ti,ab,clm. and liquid		
	263	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/08/23
		((372/36).CCLS.) or ((257/712).CCLS.) or	US-PGPUB;	15:30
		((257/713).CCLS.) or ((257/714).CCLS.) or	EPO; JPO;	1
		((257/715).CCLS.)) and (heat adj removal	DERWENT;	
		or heat adj sink or coolant or	IBM_TDB	1
		cooling).ti,ab,clm. and liquid and		
		(groove or trench)		
-	27	(US-6198758-\$ or US-6310900-\$ or	USPAT;	2002/08/23
		US-3654528-\$ or US-4807022-\$ or	US-PGPUB;	18:39
		US-5729052-\$ or US-5783862-\$ or	JPO;	
		US-5864176-\$ or US-5918665-\$ or	DERWENT	
		US-6157077-\$ or US-6274912-\$ or		I .
		US-6347050-\$ or US-5801442-\$ or		
		US-4712609-\$ or US-3764935-\$ or		
		US-5241450-\$ or US-4791634-\$ or		
		US-5812570-\$ or US-6307871-\$).did. or		1
		(US-20010004370-\$).did. or (JP-02257683-\$		
		or JP-63073584-\$ or JP-09102568-\$ or		
		JP-08227953-\$ or JP-08139479-\$).did. or		
		(JP-09102568-\$ or EP-715352-\$ or		
*		JP-06139479-\$).did.		

 5	((US-6198758-\$ or US-6310900-\$ or US-3654528-\$ or US-4807022-\$ or US-5729052-\$ or US-5783862-\$ or US-5864176-\$ or US-5918665-\$ or	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/23 18:39
	US-6157077-\$ or US-6274912-\$ or US-6347050-\$ or US-5801442-\$ or US-4712609-\$ or US-3764935-\$ or US-5241450-\$ or US-4791634-\$ or US-5812570-\$ or US-6307871-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$ or JP-09102568-\$ or JP-08227953-\$ or JP-08139479-\$).did. or (JP-09102568-\$ or LP-715352-\$ or	IBM_TDB	
2	JP-08139479-\$).did.) and laser adj diode ("4791634").PN.	USPAT; US-PGPUB; EPO; JPO;	2002/08/24 14:12
0	jp-8227953\$-\$.did.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2002/08/24 14:13
2	jp-08227953\$-\$.did.	EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/08/24
21	gengenle in and less	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	14:13
21	zengerle.in. and heat	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/24 15:25
4	zengerle.in. and power adj semiconductor adj component	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/24 15:26
4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/10 14:06
127	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:18
	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24
103	flow) (((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and heat adj sink.ti,ab,clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24

	4	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:32
-	5	laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink (((372/43) or (372/44) or (372/45) or (372/46) or (372/49) or (372/49) or (372/34) or	USPAT; US-PGPUB; EPO; JPO;	2003/05/10
:		(372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or	DERWENT; IBM_TDB	
		flow) and (groove or slit) near12 heat		
_	4	adj sink 773510.ap.	USPAT; US-PGPUB;	2003/05/10 15:49
	1627	(257/678).CCLS.	EPO; JPO; DERWENT; IBM_TDB	2002/05/12
	1027	(2377 676). CCB3.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12
-	36	((257/678).CCLS.) and heat adj sink.ti,ab,clm. and (liquid or water or flow or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:39
-	109	hayashi.in. and heat adj sink.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:40
-	18	hayashi.in. and laser.ti,ab,clm. and heat adj sink.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 13:42
-	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:54
:	1442	heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:56
-	3	lsi and (heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 13:59
-	2	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:00
-	4	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:09

- 49	<pre>l semiconductor adj laser near6 heat adj sink.ti,ab,clm.</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:09
- 24	9 semiconductor adj laser near3 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:11
-	<pre>1 (semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and liquid adj coolant</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 14:12
_ 3	5 (semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and copper	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
_	2 jp-08227953\$-\$.did.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 14:14
-	2 ("3351698").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/12 15:22
-	0 ("heat adj sink near20 laser near20 electrode near20 copper").PN.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/12 15:22
- 1	9 heat adj sink near20 laser near20 electrode near20 copper	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/05/12 15:53
-	0 top adj electrode nearl2 bottom adj electrode near20 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 15:55
- 4	4 "electrodes" near12 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 15:56
- 2	"electrodes" near6 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 15:56
-	8 "electrodes" near3 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:02
· =	4 773510.ap.	IBM_TDB USPAT; US-PGPUB; EFO; JFO; DERWENT;	2003/05/12
- 211	8 heat adj sink nearl2 electrode	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:07

_	4	773510.ap.	USPAT; US-PGPUB;	2003/05/12 19:18
			EPO; JPO; DERWENT; IBM TDB	19.10
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:34
-	2	guiding adj (hole or through-hole or aperture) near12 heat adj sink	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:51
-	115	(hole or through-hole or aperture) near12 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 19:53
_	103	(hole or through-hole or aperture) near6 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:55
_	57	(hole or through-hole or aperture) near3 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:56
_	3	(hole or through-hole or aperture) near3 (guide or guiding) near12 heat adj sink near12 (liquid or water or coolant) and heat adj sink.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 19:59
-	2	jp-09102568\$-\$.did.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	2	jp-08227953\$-\$.did.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 20:01
-	3	("5785754").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 20:30
_	0	("heat adj sink near12 (leak or leakage or leaking) near12 rubber").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12 20:30
-	0	heat adj sink near12 (leak or leakage or leaking) near12 rubber	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/12
-	0	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber)	IBM_TDB USPAT; US-PGPUB; EPO, JPO, DERWENT; IBM TDB	2003/05/12
_	20	heat adj sink nearl2 (leak or leakage or leaking) nearl2 (elastic rubber insulating insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 21:09

-	2 jp-08181392\$-\$.did.	USPAT;	2003/05/12
		US-PGPUB;	21:09
		EPO; JPO;	
		DERWENT;	
		IBM TDB	